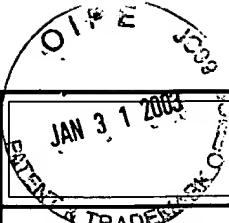
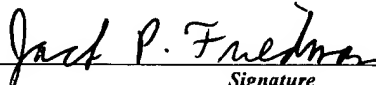
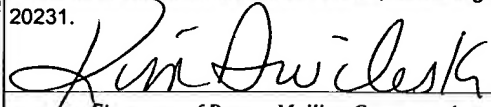


2823

 TRANSMITTAL LETTER (General - Patent Pending)		Docket No. END920010026US1	
In Re Application Of: Bernier et al.			
Serial No. 09/885,853	Filing Date 6/20/2001	Examiner William D. Coleman	Group Art Unit 2823
Title: EXTENSION OF FATIGUE LIFE FOR C4 SOLDER BALL TO CHIP CONNECTION			
<u>TO THE ASSISTANT COMMISSIONER FOR PATENTS:</u>			
Transmitted herewith is: Amendment			
in the above identified application.			
<input checked="" type="checkbox"/> No additional fee is required. <input type="checkbox"/> A check in the amount of _____ is attached. <input checked="" type="checkbox"/> The Assistant Commissioner is hereby authorized to charge and credit Deposit Account No. 09-0457(IBM) as described below. A duplicate copy of this sheet is enclosed.			
<input type="checkbox"/> Charge the amount of _____ <input checked="" type="checkbox"/> Credit any overpayment. <input checked="" type="checkbox"/> Charge any additional fee required.			
 _____ Signature		Dated: 1/28/2003	
Jack P. Friedman Reg. No. 44,688 Schmeiser, Olsen & Watts 3 Lear Jet Lane, Suite 201 Latham, NY 12110 (518) 220-1850		RECEIVED FEB - 3 2003 TECHNOLOGY CENTER 2800	
CC:		I certify that this document and fee is being deposited on 1/28/2003 with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and is addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.  Signature of Person Mailing Correspondence Kim Dwileski Typed or Printed Name of Person Mailing Correspondence	



7/A
2/6/03
Mullish

THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Bernier *et al.*

Art Unit: 2823

Serial No.: 09/885,853 ✓

Dkt. No.: END920010026US1

Filed: 6/20/01 ✓

Examiner: William D. Coleman

Title: **EXTENSION OF FATIGUE LIFE FOR C4 SOLDER BALL TO CHIP CONNECTION**

Commissioner for Patents
Washington, DC 20231

Sir:

This paper is being filed in response to a Office Action dated November 8, 2002 in connection with the above-identified application. Reconsideration and allowance are respectfully requested in view of the Amendments and Remarks below.

Amendment

In the Claims

✓
Please cancel claim 19. No claims are amended herein in the present office action response. Currently pending claims 1-6, 9-18, and 20 for consideration by the Examiner are as follows:

1. An electronic structure, comprising:

a semiconductor substrate having a first electrically conductive pad thereon;

an organic substrate having a second electrically conductive pad thereon, wherein a

RECEIVED
FEB - 3 2003
TECHNOLOGY CENTER 2800